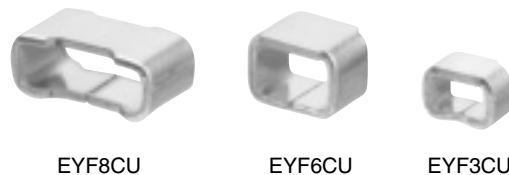


Chip Ring

Type: **EYF3CU, 6CU, 8CU**



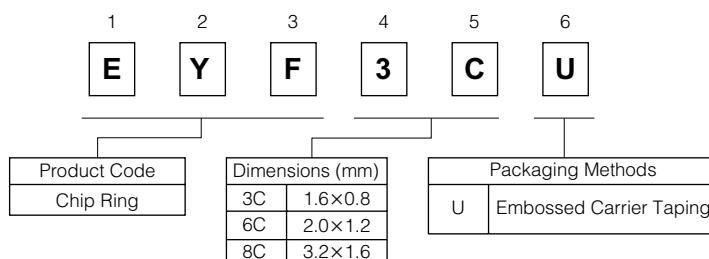
■ Features

- High reliability The folded metal sheet structure provides high robustness and a reliable connection suitable for a signal measuring terminal.
- Ease of placement The taping package supports automatic placement machines.
- Soldering Supports reflow and flow soldering.

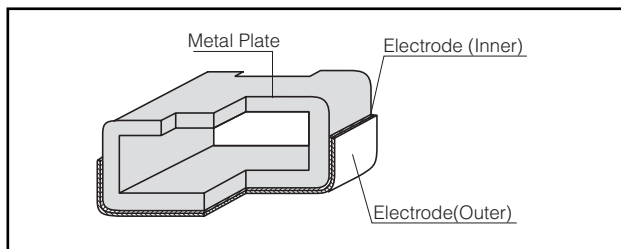
■ Recommended Applications

- To be mounted on printed circuit boards of general electronic equipment as a signal measuring terminal.

■ Explanation of Part Numbers



■ Construction

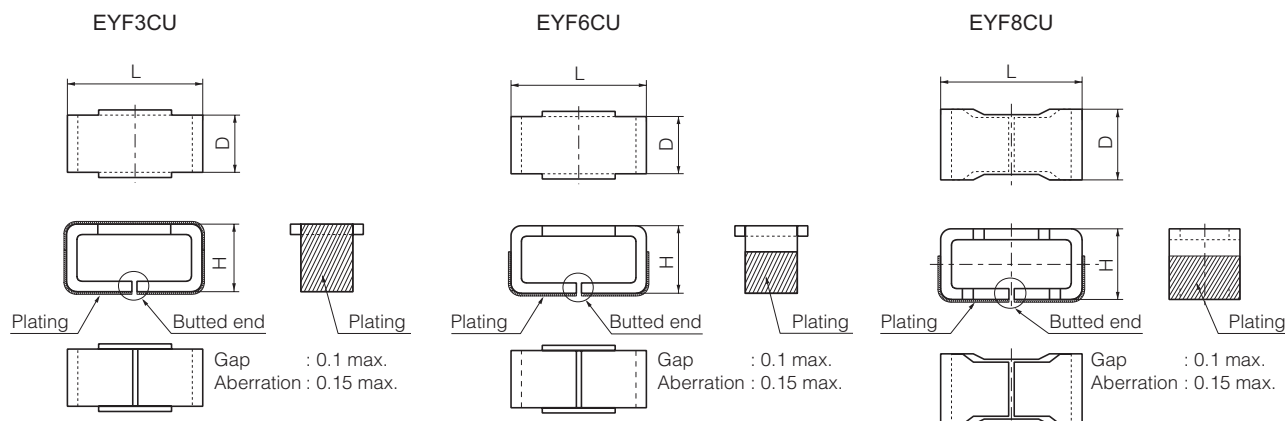


The electrodes (internal and external electrodes) of EYF3CU are entirely formed on the outer surface by plating. The inner wall and the end surfaces are not plated.

■ Ratings

Part Number	Rated Current (A)	Conductor (mΩ)
EYF3CU	2	50
EYF6CU		
EYF8CU		

■ Dimensions in mm (not to scale)



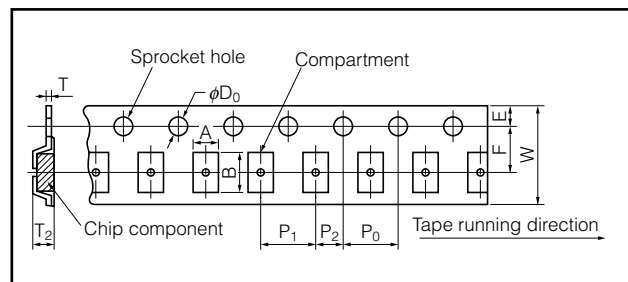
Part Number	Dimensions (mm)			Mass (Weight) [mg/pc.]
	L	D	H	
EYF3CU	1.60 ^{+0.15} _{-0.10}	0.80 ^{+0.10}	1.15 ^{+0.15}	6
EYF6CU	2.00 ^{+0.20} _{-0.10}	1.25 ^{+0.15}	1.45 ^{+0.15}	12
EYF8CU	3.20 ^{+0.20}	1.60 ^{+0.20}	1.25 ^{+0.15}	18

■ Packaging Methods (Taping)

● Standard Quantity

Part Number	Kind of Taping	Pitch (P ₁)	Quantity
EYF3CU	Embossed Carrier Taping	4 mm	2000 pcs./reel
EYF6CU			
EYF8CU			

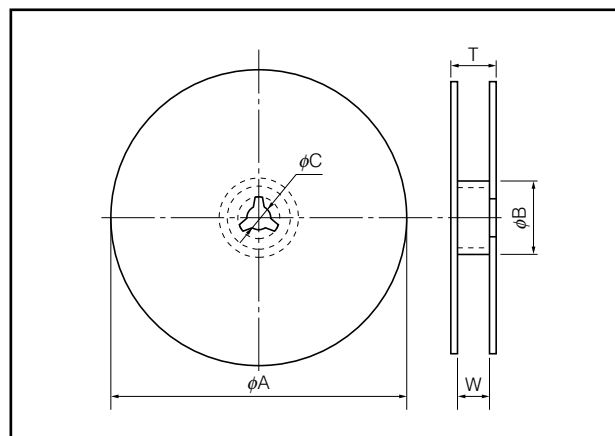
● Embossed Carrier Taping



Dimensions (mm)	Type	A	B	W	F	E	P ₁
	3C	1.20 ^{±0.10}	1.80 ^{±0.10}	8.00 ^{±0.30}	3.50 ^{±0.05}	1.75 ^{±0.10}	4.00 ^{±0.10}
	6C	1.65 ^{±0.10}	2.20 ^{±0.10}				
	8C	1.85 ^{±0.10}	3.45 ^{±0.10}				

Dimensions (mm)	Type	P ₂	P ₀	φD ₀	T	T ₂
	3C	2.00 ^{±0.05}	4.00 ^{±0.10}	1.50 ^{+0.10} ₋₀	0.27 ^{±0.05}	1.60 ^{±0.10}
	6C					1.90 ^{±0.10}
	8C					1.80 ^{±0.10}

● Taping Reel



Dimensions (mm)	φA	φB	φC	W	T
	180.0 ⁰ _{-3.0}	60 min.	13.0 ^{±1.0}	9.0 ^{±1.0}	11.4 ^{±2.0}

⚠ Safety Precautions

The following are precautions for individual products. Please also refer to the precautions common to Fixed Resistors shown on page ER3 of this catalog.

1. As the chip ring surface is conductive, it cannot connect conductor traces if solder resists are not provided for the traces. As a result, it cannot serve as a jumper chip.
2. Check the mounting conditions before use. The inside of the chip ring is hollow. Some mounters have various component detection functions in order to maximize the mounting accuracy. Since the chip ring is hollow, it may cause misjudgment during the component detection, preventing it from being mounted.
3. The maximum soldering temperature should be 300 °C. Otherwise, solder may adhere to portions that are not plated.
4. After mounting, the maximum load applied to the chip ring by a probe or a measuring needle should be 9.8 N.

⚠ Safety Precautions (Common precautions for Fixed Resistors)

- When using our products, no matter what sort of equipment they might be used for, be sure to make a written agreement on the specifications with us in advance. The design and specifications in this catalog are subject to change without prior notice.
- Do not use the products beyond the specifications described in this catalog.
- This catalog explains the quality and performance of the products as individual components. Before use, check and evaluate their operations when installed in your products.
- Install the following systems for a failsafe design to ensure safety if these products are to be used in equipment where a defect in these products may cause the loss of human life or other significant damage, such as damage to vehicles (automobile, train, vessel), traffic lights, medical equipment, aerospace equipment, electric heating appliances, combustion/gas equipment, rotating equipment, and disaster/crime prevention equipment.
- * Systems equipped with a protection circuit and a protection device
- * Systems equipped with a redundant circuit or other system to prevent an unsafe status in the event of a single fault

(1) Precautions for use

- These products are designed and manufactured for general and standard use in general electronic equipment (e.g. AV equipment, home electric appliances, office equipment, information and communication equipment)
- These products are not intended for use in the following special conditions. Before using the products, carefully check the effects on their quality and performance, and determine whether or not they can be used.
 1. In liquid, such as water, oil, chemicals, or organic solvent
 2. In direct sunlight, outdoors, or in dust
 3. In salty air or air with a high concentration of corrosive gas, such as Cl₂, H₂S, NH₃, SO₂, or NO₂
 4. Electric Static Discharge (ESD) Environment
 - These components are sensitive to static electricity and can be damaged under static shock (ESD). Please take measures to avoid any of these environments.
 - Smaller components are more sensitive to ESD environment.
 5. Electromagnetic Environment
 - Avoid any environment where strong electromagnetic waves exist.
 6. In an environment where these products cause dew condensation
 7. Sealing or coating of these products or a printed circuit board on which these products are mounted, with resin or other materials
- These products generate Joule heat when energized. Carefully position these products so that their heat will not affect the other components.
- Carefully position these products so that their temperatures will not exceed the category temperature range due to the effects of neighboring heat-generating components. Do not mount or place heat-generating components or inflammables, such as vinyl-coated wires, near these products .
- Note that non-cleaning solder, halogen-based highly active flux, or water-soluble flux may deteriorate the performance or reliability of the products.
- Carefully select a flux cleaning agent for use after soldering. An unsuitable agent may deteriorate the performance or reliability. In particular, when using water or a water-soluble cleaning agent, be careful not to leave water residues. Otherwise, the insulation performance may be deteriorated.

(2) Precautions for storage

The performance of these products, including the solderability, is guaranteed for a year from the date of arrival at your company, provided that they remain packed as they were when delivered and stored at a temperature of 5 °C to 35 °C and a relative humidity of 45 % to 85 %.

Even within the above guarantee periods, do not store these products in the following conditions. Otherwise, their electrical performance and/or solderability may be deteriorated, and the packaging materials (e.g. taping materials) may be deformed or deteriorated, resulting in mounting failures.

1. In salty air or in air with a high concentration of corrosive gas, such as Cl₂, H₂S, NH₃, SO₂, or NO₂
2. In direct sunlight

<Package markings>

Package markings include the product number, quantity, and country of origin. In principle, the country of origin should be indicated in English.